



Feature Papers in 'Electrical, Electronics and Communications Engineering' Section

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Message from the Guest Editors

Electrical, electronics, and communications engineering are used in a large variety of application fields.

The main aim of this Special Issue is to bring together researchers active in the innovative developments of devices, schemes, instrumentation, materials and applications of systems exploiting electrical, electronics, and communications engineering.

Works addressing the wide aspects of this technology are sought, including, but not limited to, recent progresses in: novel devices and schemes with relative applications; dedicated instrumentation (hardware, applications and measurement methodologies); sensor, device and material characterization; smart systems.

A special emphasis of this Special Issue will be the current state-of-the-art and emerging trends.

Prospective authors are invited to submit feature papers on topics related to “*Electrical, Electronics and Communications Engineering*”.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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